



DIM.	MIN.	TYP.	MAX.
* A	7.70		7.90
* B	4.30		4.50
C	-----		1.20
E	6.20		6.60
F		7.15	
H	0.05		0.15
J	0.17		0.30
L	0.45		0.75
P		0.65	
T	0.08		0.20
X	0°		8°
Y		12°	

NOTE :

* A & B are reference data and do not include mold deflash or protrusions.

All dimensions in mm

Angles are in degrees



CML Microcircuits

COMMUNICATION SEMICONDUCTORS

TITLE 24-pin TSSOP Package	DRAWING No. E2 (TN)	
	D'WN S.D.F.	© C.M.L. 2004
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